

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3781098

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	RELEASE OF SECURITY INTEREST
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SILICON VALLEY BANK	03/11/2016
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	HEXATECH, INC.
<b>Street Address:</b>	991 AVIATION PARKWAY
<b>Internal Address:</b>	SUITE 800
<b>City:</b>	MORRISVILLE
<b>State/Country:</b>	NORTH CAROLINA
<b>Postal Code:</b>	27560
<b>PROPERTY NUMBERS Total: 2</b>	
<b>Property Type</b>	<b>Number</b>
<b>Patent Number:</b>	8974726
<b>Patent Number:</b>	8766274
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(919)821-6800
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	919-821-1220
<b>Email:</b>	gcollins@smithlaw.com
<b>Correspondent Name:</b>	GRACE S COLLINS
<b>Address Line 1:</b>	150 FAYETTEVILLE STREET
<b>Address Line 2:</b>	SUITE 2300
<b>Address Line 4:</b>	RALEIGH, NORTH CAROLINA 27601
<b>ATTORNEY DOCKET NUMBER:</b>	9511.1
<b>NAME OF SUBMITTER:</b>	GRACE S COLLINS
<b>SIGNATURE:</b>	/s/ Grace S Collins
<b>DATE SIGNED:</b>	03/14/2016
This document serves as an Oath/Declaration (37 CFR 1.63).	
<b>Total Attachments: 3</b>	
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**RELEASE OF ASSIGNMENT FOR SECURITY OF PATENTS**

THIS RELEASE is made as of this 11 day of March, 2016, by SILICON VALLEY BANK, a California corporation (the "Bank") in favor of HEXATECH, INC., a Delaware corporation ("Company").

FOR GOOD AND VALUABLE CONSIDERATION, the receipt and adequacy of which are hereby acknowledged, the Bank hereby unconditionally and expressly releases, terminates, and extinguishes any and all of its right, title and interest in and to any and all liens and security interests it may have upon the patents listed on Schedule A attached hereto and made a part hereof, which liens and security interests were established under and pursuant to that certain Intellectual Property Security Agreement, dated as of October 21, 2011, made by Company in favor of Bank, which was recorded with the United States Patent and Trademark Office on April 22, 2013 at Reel 030260/Frame 0406.

The Bank consents and agrees to execute and deliver, at the request and cost of Company, such further instruments, documents and release forms as Company may reasonably request to more effectively, release, terminate and extinguish any such liens and security interests upon such patents.

This Release shall be binding upon Bank's legal representatives, assigns and successors.

**SILICON VALLEY BANK**

By 

Name: *Patrick C. Slegers*

Title: *Director*

**SCHEDULE A**

**PATENT REGISTRATIONS**

<b>PATENT</b>	<b>PATENT APPLICATION</b>	<b>PATENT APPLICATION DATE</b>	<b>PATENT</b>	<b>ISSUE DATE</b>
<b>POLYCRYSTALLINE ALUMINUM NITRIDE MATERIAL AND METHOD OF PRODUCTION THEREOF</b>	13185544	07/19/2011	8974726	03/10/2015
<b>THERMAL EXPANSION ENGINEERING FOR POLYCRYSTALLINE ALUMINUM NITRIDE SINTERED BODIES</b>	13324261	12/13/2011	8766274	07/01/2014